

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	549	((interposer or pcb or pwb or (wiring or circuit or package or interconnection) near (board or substrate)) near4 (two or dual or multi or multiple or plural or plurality) near2 (piece))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 15:54
L3	125	((interposer or pcb or pwb or (wiring or circuit or package or interconnection) near (board or substrate)) near4 (two or dual or multi or multiple or plural or plurality) near2 (piece)) same (outer or peripheral or outside or periphery or edge or exterior or outlying or annular or ring or surrounding or ringing)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 15:55
S49	60	((interconnection or wiring or circuit) near (board or substrate) or interposer) near5 (split or gap or divided or partition\$3 or separated or separation or interval) near10 (cte or thermal near expansion or thermally near expand\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 13:45
S50	52	((interconnection or wiring or circuit) near (board or substrate) or interposer) near3 peripheral same (cte or thermal\$2 near expan\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 13:51
S51	262	((interconnection or wiring or circuit) near (board or substrate)) near5 (split or gap or divided or partition\$3 or separated or separation or interval) same (chip or die or ic) same (solder near ball or solder near bump or bga or ball near grid)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 14:02
S52	158	(substrate or interposer or pcb or pwb or wiring near board or circuit near board) near5 (trench or trenched or groove or grooved) near8 (thermal\$2 near expan\$4 or cte or thermal\$2 near mismatch\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 14:19
S53	278	((interconnection or wiring or circuit) near (board or substrate)) near4 (groove or grooved or trench or trenched) same (chip or die or ic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 14:28

## EAST Search History

S54	394	((interconnection or wiring or circuit) near (board or substrate)) near6 (ring or annular or annulus) same (chip or die or ic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 14:40
S55	85	interposer near3 (ring or peripheral or surrounding or around or enclosing or ringing or (chip or die) near2 (cavity or aperture or opening)) and (heat or thermal) near (sink or sinking or spreader or spreading) and (bga or ball near grid or solder near ball or solder near bump)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 14:41
S56	719	257/E23.004.ccls. and (stress\$4 or strain\$4 or compress\$4 or tensile or tension)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 14:48
S57	392	257/E23.194.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 14:56
S58	536	257/E23.181.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 15:13
S59	73	257/683.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 15:20
S60	50	257/666-798.ccls. and (substrate or board or pcb or pwb or interposer) near2 (segmented or segmenting or divided or separated or interval) near15 (stress\$4 or strain\$4 or tensile or tension or compressed or compressive or compression or compress or expanded or expans\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 15:24
S61	69	257/666-798.ccls. and (substrate or board or pcb or pwb or interposer) near2 (partition\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 15:29

## EAST Search History

S62	36	257/666-798.ccls. and (substrate or board or pcb or pwb or interposer) near8 (peripheral or periphery or circumferential) near8 (central) same (stress\$4 or strain\$4 or tensile or tension or compressed or compressive or compression or compress or expanded or expans\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 15:34
S63	54	257/666-798.ccls. and (substrate or board or pcb or pwb or interposer) near2 (ring) same (stress\$4 or strain\$4 or tensile or tension or compressed or compressive or compression or compress or expanded or expans\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 15:35
S64	16	257/666-798.ccls. and (substrate or board or pcb or pwb or interposer) near2 (subdivided or subdivision)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 15:36
S65	325	257/666-798.ccls. and (substrate or board or pcb or pwb or interposer) near2 (slot or slotted)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 15:37

# Interference Search

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L4	43	((package or packaging or housing) and (chip or die or ic or semiconductor near device) and (pcb or pwb or interposer or (wiring or circuit or interconnection) near2 (board or substrate)) near2 (peripheral or periphery or ring or ringing or annular or encircling or circling)).clm.	US-PGPUB	OR	ON	2006/08/02 16:04
L5	42	((package or packaging or housing) and (chip or die or ic or semiconductor near device) and (pcb or pwb or interposer or (wiring or circuit or interconnection) near2 (board or substrate)) near2 (separat\$4 or grooved or trenched or nonintegral or disjointed)).clm.	US-PGPUB	OR	ON	2006/08/02 16:09
L6	23	((package or packaging or housing) and (chip or die or ic or semiconductor near device) and (pcb or pwb or interposer or (wiring or circuit or interconnection) near2 (board or substrate)) near4 (two or dual or multi or multiple or plural or plurality or several) near (piece or component)).clm.	US-PGPUB	OR	ON	2006/08/02 16:08
L7	1	((package or packaging or housing) and (chip or die or ic or semiconductor near device) and (pcb or pwb or interposer or (wiring or circuit or interconnection) near2 (board or substrate)) near4 (groov\$3 or trench\$3 or partition\$3 or subdivid\$3 or hole or opening or split) near3 (cte or stress or strain or thermal near expan\$4)).clm.	US-PGPUB	OR	ON	2006/08/02 16:09
L8	38	((chip or die or ic or semiconductor near device) and (pcb or pwb or interposer or (wiring or circuit or interconnection or package) near2 (board or substrate)) near2 (peripheral or periphery or outer or outside or edge or annular or annulus) and (pcb or pwb or interposer or (wiring or circuit or interconnection or package) near2 (board or substrate)) near2 (central or core or center or inner)).clm.	US-PGPUB	OR	ON	2006/08/02 16:11